7-2834006-2 ACTIVE

Buchanan WireMate

TE Internal #: 7-2834006-2

Poke-In Connectors, Wire-to-Board, 2 Position, 4 mm Centerline, Printed Circuit Board, Height .176 in [4.48 mm], Surface Mount, 18 –

22 AWG Wire Size

View on TE.com >

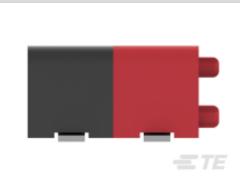


Connectors > Lighting Connectors > Poke-In Connectors > Poke-In Connector, BUCHANAN WireMate











Connector System: Wire-to-Board

Number of Positions: 2
Centerline (Pitch): 4 mm

Connector & Contact Terminates To: Printed Circuit Board

Connector Height: 4.48 mm [.176 in]

All Poke-In Connector, BUCHANAN WireMate (51)

Features

Product Type Features

Product Type Features	
Product Line	Poke-In
Connector System	Wire-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	2
Electrical Characteristics	
Operating Voltage	400 VAC
Body Features	
Primary Product Color	Natural
Contact Features	
PCB Contact Termination Area Plating Material Finish	Matte
Contact Underplating Material	Nickel



	
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Current Rating (Max)	6 A
Termination Features	
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	4 mm
Dimensions	
Compatible Insulation Diameter Range	2.1 mm
Connector Height	4.48 mm[.176 in]
Wire Size	18 – 22 AWG
Industry Standards	
Compatible With Agency/Standards Products	UL
Compatible With Approved Standards Products	UL 1977, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	

Product Compliance

Packaging Method

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

Tape & Reel

Product Compliance Disclaimer



This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Customers Also Bought

















Documents

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_7-2834006-2_B.2d_dxf.zip



English

Customer View Model

ENG_CVM_CVM_7-2834006-2_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_7-2834006-2_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

Modular Releasable Poke-in datasheet

English

BUCHANAN WireMate Connectors Brochure

BUCHANAN WireMate Connectors Brochure

English

Modular Releasable Poke-in datasheet (Chinese)

Product Specifications

Application Specification

English